



OMAP-L138 SOM-M1 Hardware Specification

Hardware Documentation

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Please check www.logicpd.com for the latest revision of this document, product change notifications, and additional documentation.

Table of Contents

| | | |
|----------|--|-----------|
| 1 | Introduction | 1 |
| 1.1 | Product Overview | 1 |
| 1.2 | Abbreviations, Acronyms, & Definitions | 1 |
| 1.3 | Nomenclature | 2 |
| 1.4 | Scope of Document | 2 |
| 1.5 | Additional Documentation Resources | 2 |
| 2 | Functional Specification | 4 |
| 2.1 | Processor | 4 |
| 2.1.1 | OMAP-L138 Processor | 4 |
| 2.1.2 | OMAP-L138 Processor Block Diagram | 5 |
| 2.2 | SOM Interface | 5 |
| 2.2.1 | OMAP-L138 SOM-M1 Block Diagram | 6 |
| 2.3 | Mechanical Specifications | 6 |
| 2.3.1 | Mechanical Characteristics of SOM | 6 |
| 2.3.2 | Interface Connectors | 7 |
| 2.3.3 | OMAP-L138 SOM-M1 Mechanical Drawings | 7 |
| 2.3.4 | Example OMAP-L138 SOM-M1 Retention Methods | 7 |
| 2.4 | Temperature Specifications | 7 |
| 3 | Electrical Specification | 8 |
| 3.1 | Absolute Power Maximum Ratings | 8 |
| 3.2 | Recommended Power Operating Conditions | 8 |
| 4 | Peripheral Specification | 9 |
| 4.1 | Clocks | 9 |
| 4.2 | Memory | 9 |
| 4.2.1 | Mobile DDR | 9 |
| 4.2.2 | SPI Flash | 9 |
| 4.3 | 10/100 Ethernet PHY | 9 |
| 4.4 | Display Interface | 10 |
| 4.5 | Serial Interfaces | 10 |
| 4.5.1 | UART0-2 | 10 |
| 4.5.2 | SPI0/1 | 10 |
| 4.5.3 | I2C0/1 | 11 |
| 4.5.4 | McBSP0/1 | 11 |
| 4.5.5 | McASP | 11 |
| 4.6 | USB Interface | 11 |
| 4.7 | ADC/Touch Interface | 11 |
| 4.8 | General Purpose I/O (GPIO) | 11 |
| 4.9 | Expansion/Feature Options | 12 |
| 5 | System Integration | 13 |
| 5.1 | Custom Configuration | 13 |
| 5.2 | Resets | 13 |
| 5.2.1 | Master Reset (MSTR_nRST)—Reset Input | 13 |
| 5.2.2 | SOM Reset (RESETOUTn)—Reset output | 13 |
| 5.3 | Interrupts | 14 |
| 5.4 | JTAG Debugger Interface | 14 |
| 5.5 | Power Management | 14 |
| 5.5.1 | System Power Supplies | 14 |
| 5.5.1.1 | 5V | 14 |
| 5.5.1.2 | USB0_VBUS | 14 |
| 5.5.1.3 | MAIN_BATT_IN | 15 |
| 5.5.1.4 | VRTC_IN | 15 |
| 5.5.2 | Dual Voltage I/O | 15 |
| 5.5.3 | System Power Management | 15 |

| | | |
|--|---|-----------|
| 5.5.4 | Microcontroller | 16 |
| 5.6 | ESD Considerations | 16 |
| 6 | Memory & I/O Mapping..... | 17 |
| 7 | Pin Descriptions & Functions | 18 |
| 7.1 | J1 Connector 100-Pin Descriptions | 18 |
| 7.2 | J2 Connector 100-Pin Descriptions | 24 |
| 7.3 | J3 Connector 100-Pin Descriptions | 28 |
| Appendix A: OMAP-L138 SOM-M1 Mechanical Drawing | | 32 |
| Appendix B: Example OMAP-L138 SOM-M1 Retention Methods..... | | 34 |

Table of Figures

| | |
|---|---|
| Figure 2.1: OMAP-L138 Processor Block Diagram | 5 |
| Figure 2.2: OMAP-L138 SOM-M1 Block Diagram | 6 |

1 Introduction

1.1 Product Overview

The OMAP-L138 System on Module (SOM) is a compact, product-ready hardware and software solution that fast forwards embedded designs while reducing risk and controlling cost.

Based on Texas Instruments' OMAP-L138 processor and designed in the SOM-M1 form factor, the OMAP-L138 module offers essential features for handheld and embedded networking applications. The OMAP-L138 SOM-M1 features the superset OMAP-L138 processor, but also supports the TMS320C6748 digital signal processor (DSP).

The OMAP-L138 SOM-M1 brings the industry leading low power ARM926 core to a small, off-the-shelf solution. The standard SOM-M1 form factor allows developers to reuse existing baseboard designs when upgrading to new OMAP processors, which extends roadmap possibilities for their end-product.

Two Zoom™ Development Kit options allow developers to choose the platform best suited to their application needs. By starting with the corresponding Zoom Development Kit, engineers can write application software on the same hardware that will be used in their final product.

The compact size of the OMAP-L138 SOM-M1 is ideal for medical patient monitoring wearables and other portable instrumentation applications; the built-in Serial ATA (SATA) controller provides fast access to large capacity storage devices. For medical, industrial, audio, and communication products, the OMAP-L138 SOM-M1 allows for powerful versatility, long-life, and greener products.

1.2 Abbreviations, Acronyms, & Definitions

| | |
|-------|------------------------------------|
| ADC | Analog to Digital Converter |
| BOM | Bill of Materials |
| BSP | Board Support Package |
| BTB | Board-to-Board |
| DAC | Digital to Analog Converter |
| DMA | Direct Memory Access |
| DSP | Digital Signal Processor |
| EDMA | Enhanced Direct Memory Access |
| EMIFA | External Memory Interface |
| ESD | Electrostatic Discharge |
| FIFO | First In First Out |
| HPI | Host Port Interface |
| GPIO | General Purpose Input Output |
| GPMC | General Purpose Memory Controller |
| Hi-Z | High Impedance |
| I2C | Inter-Integrated Circuit |
| I2S | Inter-Integrated Circuit Sound |
| IC | Integrated Circuit |
| I/O | Input/Output |
| IRQ | Interrupt Request |
| LCD | Liquid Crystal Display |
| LDO | Low Dropout (Regulator) |
| McASP | Multi-channel Audio Serial Port |
| McBSP | Multi-channel Buffered Serial Port |
| mDDR | Mobile Double Data Rate (RAM) |

| | |
|--------|---|
| MDIO | Management Data Input/Output |
| MMU | Memory Management Unit |
| MPU | Memory Protection Unit (ARM processor core) |
| OTG | On-the-Go (USB) |
| PCB | Printed Circuit Board |
| PCMCIA | Personal Computer Memory Card International Association (PC Cards) |
| PHY | Physical Layer |
| PLL | Phase Lock Loop |
| PWM | Pulse Width Modulation |
| RTC | Real Time Clock |
| SATA | Serial ATA |
| SDRAM | Synchronous Dynamic Random Access Memory |
| SOM | System on Module |
| SOM-M1 | SOM form factor type used for the OMAP-L138 and TMS320C6748 modules |
| SPI | Standard Programming Interface |
| STN | Super-Twisted Nematic (LCD) |
| TFT | Thin Film Transistor (LCD) |
| TI | Texas Instruments |
| TSC | Touch Screen Controller |
| UART | Universal Asynchronous Receive Transmit |
| uPP | Universal Parallel Port |
| USB | Universal Serial Bus |
| VLIW | Very Long Instruction Word |
| VPIF | Video Port Interface |

1.3 Nomenclature

- The terms “SOM” and “SOM-M1” are used interchangeably throughout this document and can be assumed to mean the same thing within this text. The SOM-M1 is a specific form factor type of Logic’s SOM.
- TMS320C6748, C6748, and C674x can be assumed to all represent the TMS320C6748 DSP core.

1.4 Scope of Document

- This Hardware Specification is unique to the design and use of the OMAP-L138 SOM-M1 as designed by Logic and does not intend to include information outside of that scope. Detailed information about the Texas Instruments (TI) OMAP-L138 processor or any other device component on the SOM can be found in their respective manuals and specification documents; please see Section 1.5 for additional resources.
- This Hardware Specification applies to both the OMAP-L138 SOM-M1 and TMS320C6748 SOM-M1. The OMAP-L138 processor and TMS320C6758 DSP are identical, with the exception that the OMAP-L138 is a dual-core processor with an ARM9 core and a C674x core. Both processors—and therefore both SOMs—have the same peripheral set and the same pin functions.

1.5 Additional Documentation Resources

The following documents or documentation resources are referenced within this Hardware Specification.

- TI’s *OMAP-L138 Low-Power Applications Processor Datasheet, User Guides, Application Notes, White Papers, and Errata*
<http://www.ti.com/omap-l138-prprod1>

- TI's *TPS65070 Datasheet*
<http://focus.ti.com/docs/prod/folders/print/tps65070.html>
- USB 2.0 Specification, available from USB.org
<http://www.usb.org/developers/docs/>
- U-Boot documentation
<http://www.denx.de/wiki/U-Boot/WebHome>
- Logic *OMAP-L138 Baseboard BOM, Schematic, and Layout*
<http://support.logicpd.com/downloads/1216/>
- Logic *OMAP-L138 SOM-M1 BOM, Schematic, and Layout* (128 MB mDDR configuration included with the EVM Development Kit)
<http://support.logicpd.com/downloads/1215/>
- Logic *OMAP-L138 SOM-M1 BOM, Schematic, and Layout* (64 MB mDDR configuration included with the eXperimenter Kit)
<http://support.logicpd.com/downloads/1227/>
- Logic *TMS320C6748 SOM-M1 BOM, Schematic, and Layout* (included with the EVM Development Kit)
<http://support.logicpd.com/downloads/1228/>

2 Functional Specification

2.1 Processor

2.1.1 OMAP-L138 Processor

The OMAP-L138 SOM-M1 uses TI's high-performance OMAP-L138 processor. This device contains two cores: an ARM926EJ-S MPU core and a C674x VLIW DSP core. The OMAP-L138 provides many integrated on-chip peripherals, including:

- ARM® ARM926EJ-S™ RISC core
- C674x VLIW DSP core
- Integrated LCD Controller
 - Up to 1024 x 1024 x 16 bit color
- Three UARTs
- I2S codec interface
- Universal Serial Bus (USB)
 - One high-speed USB 2.0 On-the-Go (OTG) interface
 - One full-speed USB 1.1 host interface
- Serial ATA Controller
 - SATA I (1.5Gb/s) or SATA II (3Gb/s)
- Many general purpose I/O (GPIO) signals
- Programmable timers
- Real time clock (RTC)
- Low power modes

IMPORTANT NOTE: The OMAP-L138 processor is heavily multiplexed; using one peripheral may preclude the use of another. Users should carefully review the processor pinout, SOM pinout, and OMAP-L138 multiplexing table. See TI's *OMAP-L138 Low-Power Applications Processor Datasheet*, User Guides, and Application Notes for additional information.

IMPORTANT NOTE: Please visit TI's website for errata on the OMAP-L138.

2.1.2 OMAP-L138 Processor Block Diagram

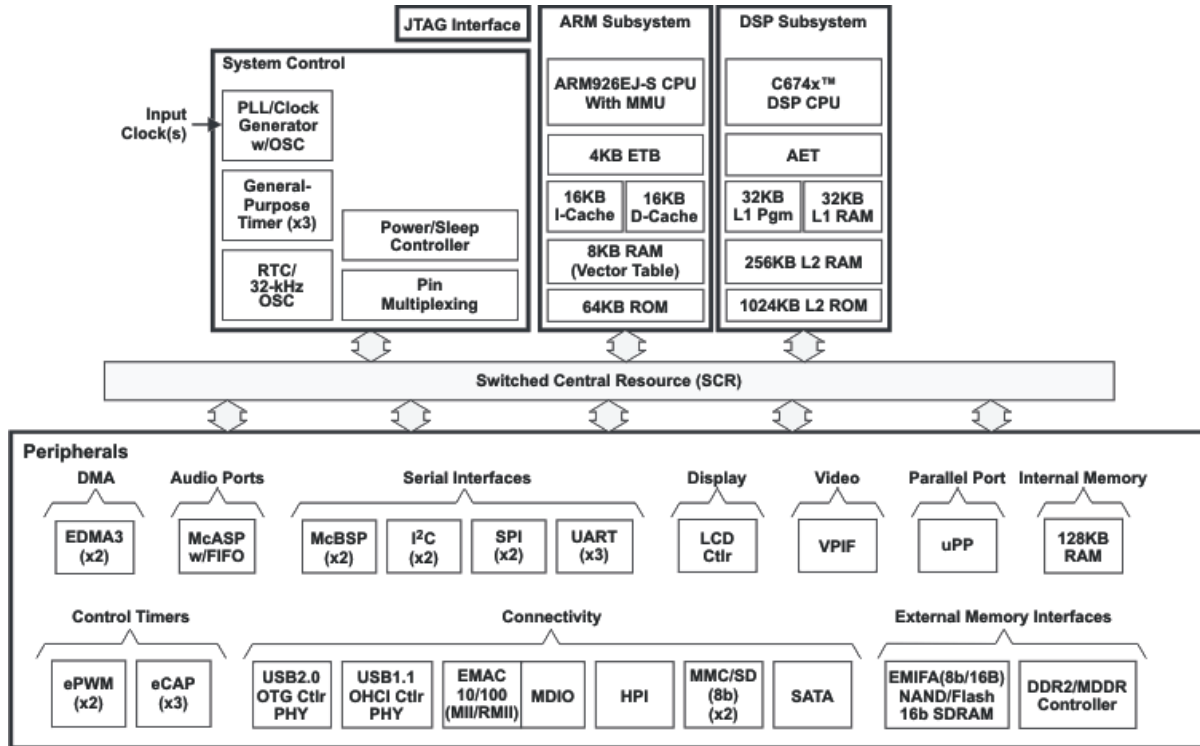


Figure 2.1: OMAP-L138 Processor Block Diagram

Note: The block diagram pictured above comes from TI's *OMAP-L138 Low-Power Applications Processor Data Sheet* (document number SPRS586–June 2009). Available from TI's website: <http://www.ti.com/lit/gpn/omap-138>.

2.2 SOM Interface

Logic's common SOM interface allows for easy migration to new processors and technology. Logic is constantly researching and developing new technologies to improve performance, lower cost, and increase feature capabilities. By using the common SOM footprint, it is possible to take advantage of Logic's work without having to re-spin the old design in certain cases dependent upon peripheral usage. Contact Logic sales for more information (product.sales@logicpd.com).

In fact, encapsulating a significant amount of your design onto the SOM reduces any long-term risk of obsolescence. If a component on the SOM design becomes obsolete, Logic will simply design for an alternative part that is transparent to your product. Furthermore, Logic tests all SOMs prior to delivery, decreasing time-to-market and ensuring a simpler and less costly manufacturing process.

2.2.1 OMAP-L138 SOM-M1 Block Diagram

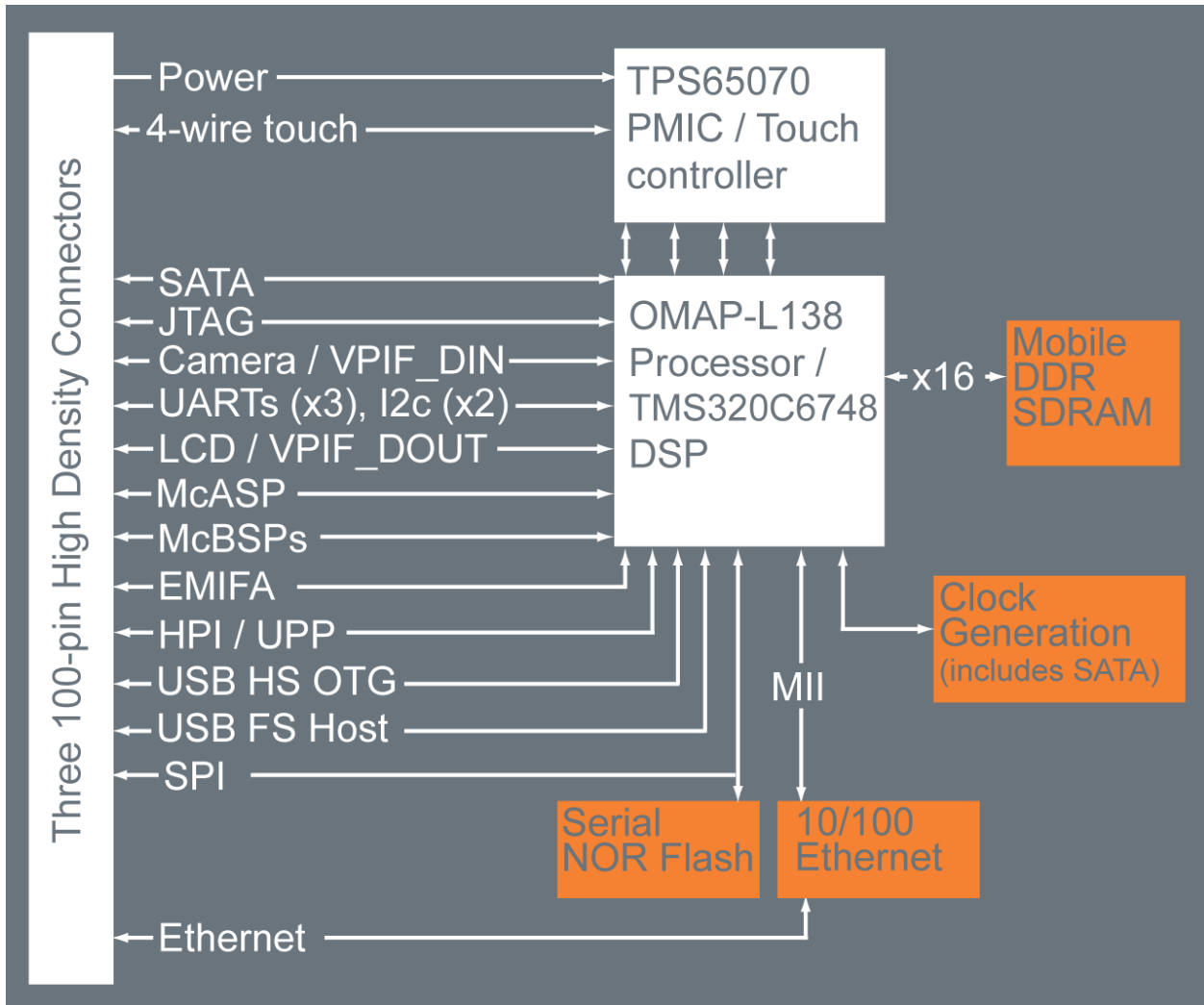


Figure 2.2: OMAP-L138 SOM-M1 Block Diagram

2.3 Mechanical Specifications

2.3.1 Mechanical Characteristics of SOM

| Parameter | Min | Typical | Max | Unit | Notes |
|-----------------------------|-----|---------------|-----|--------|-------|
| Dimensions | — | 30 x 40 x 4.1 | — | mm | 1 |
| Weight | — | 7 | — | Grams | 2 |
| Connector Insertion/Removal | — | 30 | — | Cycles | — |

Notes:

1. The OMAP-L138 SOM-M1 in the Zoom OMAP-L138 EVM Development Kit includes power measurement circuitry along one edge of the SOM. This additional circuitry increases the PCB size to 33.7 x 40 x 4.1 mm. All other OMAP-L138 SOM-M1 modules, including those available in production volumes, are the typical size listed above.
2. May vary depending on SOM configuration.

2.3.2 Interface Connectors

The OMAP-L138 SOM-M1 connects to a PCB baseboard through three 100-pin board-to-board (BTB) socket connectors.

| Ref Designator | Manufacturer | SOM Connector P/N | Mating Connector P/N |
|----------------|--------------|----------------------|----------------------|
| J1, J2, J3 | Hirose | DF40C-100DP-0.4V(51) | DF40C-100DS-0.4V(51) |

2.3.3 OMAP-L138 SOM-M1 Mechanical Drawings

Please see Appendix A for mechanical drawings of the OMAP-L138 SOM-M1 and recommended baseboard footprint layout.

2.3.4 Example OMAP-L138 SOM-M1 Retention Methods

Please see Appendix B for mechanical drawings demonstrating three possible retention methods for the OMAP-L138 SOM-M1. These drawings are only meant to serve as possible solutions and should not be considered final designs for retention.

2.4 Temperature Specifications

| Parameter | Min | Typical | Max | Unit | Notes |
|----------------------------------|-----|---------|-----|------|-------|
| Commercial Operating Temperature | 0 | 25 | 70 | °C | — |
| Industrial Operating Temperature | -40 | 25 | 85 | °C | — |
| Storage Temperature | -40 | 25 | 85 | °C | — |

CAUTION: Systems using the SATA interface on the OMAP-L138 SOM-M1 may require additional heat dissipation techniques in order to comply with the high end of the system temperature limitation. It is the responsibility of the engineer to ensure the OMAP-L138 SOM-M1 maintains a safe operating temperature within the system.

3 Electrical Specification

3.1 Absolute Power Maximum Ratings

| Parameter | Symbol | Rating | Unit |
|-------------------------------|--------------|------------|------|
| DC 5 V Supply Voltage | 5V | 0.0 to 7.0 | V |
| DC Main Battery Input Voltage | MAIN_BATT_IN | 0.0 to 7.0 | V |
| RTC Backup Battery Voltage | BACKUP_BATT | 0.0 to 7.0 | V |

NOTE: These stress ratings are only for transient conditions. Operation at, or beyond, absolute maximum rating conditions may affect reliability and cause permanent damage to the SOM and its components.

3.2 Recommended Power Operating Conditions

| Parameter | Min | Typical | Max | Unit | Notes |
|-------------------------------|------------------|---------|------------------|------|-------|
| DC Main Battery Input Voltage | 3.3 | 3.6 | 4.2 | V | 4 |
| DC 5V Voltage | 3.6 | 5.0 | 5.8 | V | 3 |
| DC 5V Active Current | — | 220 | — | mA | 5 |
| DC 5V Active Current, no SATA | — | 130 | — | mA | 6 |
| DC RTC Backup Battery Voltage | 1.8 | 3.3 | 3.6 | V | |
| Input Signal High Voltage | 0.65*VREF (1.8V) | — | VREF | V | 2 |
| | 2 (3.3V) | | | | |
| Input Signal Low Voltage | GND | — | 0.35*VREF (1.8V) | V | 2 |
| | | | 0.8 (3.3V) | | |
| Output Signal High Voltage | 2.40 (3.3V) | — | VREF | V | 2 |
| | VREF-0.45 (1.8V) | | | | |
| Output Signal Low Voltage | GND | — | 0.40 (3.3V) | V | 2 |
| | | | 0.45 (1.8V) | | |

Notes:

1. General note: CPU power rails are sequenced on the module.
2. VREF represents the peripheral I/O supply reference for the specific CPU voltage rail. For $V_{I/OH}$ and $V_{I/OL}$, different values are provided for VREF = 1.8V and 3.3V.
3. Please see Section 5.5.1.1 for detailed information about 5V usage on the OMAP-L138 SOM-M1.
4. Please see Section 5.5.1.3 for detailed information about MAIN_BATT_IN usage on the OMAP-L138 SOM-M1.
5. Measurement was taken with a system consisting of SOM, baseboard, and UI board. The SOM was running the standard U-Boot software image. This power measurement represents current consumption on the SOM only (baseboard and UI board were excluded).
6. Same setup as Note 5 with the exception that the SATA clock generator was disabled by populating R146.

4 Peripheral Specification

4.1 Clocks

The OMAP-L138 SOM-M1 contains two crystals. One crystal is used to generate clocks for the processor core(s) and peripherals. The second crystal is dedicated to the RTC module.

The OMAP-L138 processor includes on-chip Phase Locked Loops (PLLs) and signal dividers which generate all core/peripheral clocks from a single external 24.000 MHz crystal. The maximum core processor operating frequency is 300 MHz. Optionally, on-chip module PLL0 provides an output:

| SOM Pin# | SOM Net Name | OMAP-L138 Processor Pin |
|----------|--------------|----------------------------|
| J3.18 | uP_OBSCLK | CLKOUT/ UHPI_HDS2/ GP6[14] |

IMPORTANT NOTE: Please see TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides for additional information about processor clocking.

The OMAP-L138 processor also contains an on-chip Real Time Clock (RTC) module which is driven by an external 32.768 kHz crystal. The highly configurable RTC module provides a time reference to applications running on the OMAP-L138. The SOM contains a dedicated power input pin (J2.64, "VRTC_IN") and low dropout (LDO) which supplies the processor's dedicated RTC power rail (RTC_CVDD)

IMPORTANT NOTE: For more information on RTC power, see Section 5.5.1.4. For more information about software configuration of the RTC, see TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides.

4.2 Memory

4.2.1 Mobile DDR

The OMAP-L138 SOM-M1 provides volatile memory via a single mDDR chip. Please refer to the *OMAP-L138 SOM-M1 Bill of Materials (BOM)* for the memory density of your specific SOM.

Other memory densities may be available for SOMs in production volumes. Please contact Logic Sales about custom configurations if your design requires different memory densities from Logic's standard SOM configurations: product.sales@logicpd.com.

4.2.2 SPI Flash

The OMAP-L138 SOM-M1 provides non-volatile memory via an 8 MB SPI flash chip. This is also the default boot device.

Other memory densities may be available for SOMs in production volumes. Please contact Logic Sales about custom configurations if your design requires different memory densities from Logic's standard SOM configurations: product.sales@logicpd.com.

4.3 10/100 Ethernet PHY

The OMAP-L138 SOM-M1 uses an SMSC LAN8710 Ethernet PHY to provide an easy-to-use networking interface. The four analog PHY interface signals (transmit/receive) each require an

external impedance matching circuit to operate properly. Logic provides an example circuit schematic in the *OMAP-L138 Baseboard Schematics*. Please note the TX+/- and RX+/- pairs must be routed as differential pairs on the baseboard PCB.

4.4 Display Interface

The OMAP-L138 has a built-in LCD controller supporting both synchronous (raster-type) and asynchronous (memory-mapped) panels.

The synchronous (raster) module supports STN, color STN, and TFT panels at a resolution of up to 1024 x 1024 x 16-bit color.

The asynchronous (memory-mapped) module supports a broad range of displays from monochrome character displays to TFT smart LCD panels. Displays driven by this module must contain their own memory and timing circuitry.

The signals from the OMAP-L138 LCD controller can be interfaced through the expansion connectors. See TI's *OMAP-L138 Low-Power Applications Processor Datasheet* for further information on the integrated LCD controller. Logic has written drivers for panels of different types and sizes. Please contact Logic before selecting a panel for your application.

IMPORTANT NOTE: Using the internal graphics controller will affect processor performance. Selecting display resolutions and color bits per pixel will vary processor busload.

4.5 Serial Interfaces

The OMAP-L138 SOM-M1 comes with the following serial channels: UART0-2, SPI0/1, I2C0/1, McBSP0/1, and McASP. If additional serial channels are required, please contact Logic for reference designs. Please see TI's *OMAP-L138 User Guides* for further information regarding serial communications.

4.5.1 UART0-2

The OMAP-L138 SOM-M1 provides three UART ports. UART0, UART1, and UART2 are asynchronous 16C550-compatible UARTs. These UARTs are high-speed serial interfaces that use 16-byte TX and RX FIFO registers; they are capable of sending and receiving serial data simultaneously. The signals from the SOM are not RS232 level signals. The end-product design must provide an external transceiver for RS232 applications. Logic has provided an example reference design with the Zoom OMAP-L138 Development Kits. When choosing an RS232 transceiver, the designer should keep in mind cost, availability, ESD protection, and data rates.

UART2 has been configured as the main SOM serial port. The UART2 baud rate is set to a default 115.2 Kbits/sec, though it supports most common serial baud rates.

4.5.2 SPI0/1

The OMAP-L138 SOM-M1 provides two SPI ports with multiple chip selects.

SPI1 is the default boot source for the OMAP-L138 SOM-M1. A serial flash chip is attached to SPI1 CS0.

4.5.3 I2C0/1

The OMAP-L138 SOM-M1 provides two I2C ports. The clock and data signals for both ports have 4.7K pull-up resistors to their respective power rails on the SOM. Please see TI's OMAP-L138 User Guides for further information.

I2C0 has been configured as the main SOM I2C port. I2C0 is used to control/configure many ICs on the SOM as well as the OMAP-L138 Development Kits.

4.5.4 McBSP0/1

The OMAP-L138 SOM-M1 supports two Multi-channel Buffered Serial Port (McBSP) interfaces. These interfaces are primarily designed to support AC97 and IIS modes, but they can also be configured for other serial formats. However, The McBSPs are not intended to be used as high-speed interfaces.

4.5.5 McASP

The OMAP-L138 SOM-M1 supports one Multi-channel Audio Serial Port (McASP). The McASP interface supports TDM streams, I2S protocols, and DIT.

Logic has provided an example reference design with the Zoom OMAP-L138 Development Kits; this reference design interfaces the OMAP-L138 McASP to a TLV320AIC3106 audio codec.

4.6 USB Interface

The OMAP-L138 SOM-M1 supports one USB 1.1 full-speed host port and one USB 2.0 OTG port, which can function as a host or device/client. The USB 2.0 port can operate at up to 480 Mbit/sec, and the USB 1.1 port can operate at up to 12 Mbit/sec. Both the USB 1.1 and USB 2.0 controllers are internal to the OMAP-L138 processor. For more information on using both the USB host and OTG interfaces, please see TI's OMAP-L138 User Guides.

IMPORTANT NOTE: In order to correctly implement USB on the SOM, additional impedance matching circuitry may be required on the USBx_D+ and USBx_D- signals before they can be used. USB 2.0 requirements specify the signals must be routed as differential pairs with a 90 ohm differential impedance. Refer to the *USB 2.0 Specification* for detailed information.

4.7 ADC/Touch Interface

The touch screen controller (TSC) on the OMAP-L138 SOM-M1 is an integrated feature of the TPS65070 PMIC. This TSC is used to support standard 4-wire resistive touch panels. The TPS65070 is connected to the OMAP-L138 by the I2C0 interface. Please see TI's *TPS65070 Datasheet* for more information.

4.8 General Purpose I/O (GPIO)

Logic designed the OMAP-L138 SOM-M1 to be flexible and provide multiple options for analog and digital GPIO. There are numerous digital GPIO pins on the SOM that interface to the OMAP-L138. See Section 7 of this document for more information. If certain peripherals are not desired, such as the LCD controller, chip selects, IRQs, or UARTs, then more GPIO pins become available.

4.9 Expansion/Feature Options

The OMAP-L138 SOM-M1 was designed for expansion and a variable feature set, providing all the necessary control signals and bus signals to expand the user's design. Some of these signals are buffered before reaching the expansion connectors. See TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides and Logic's *OMAP-L138 SOM-M1 Schematics* for more details. Logic has experience implementing additional options, including: audio codecs, Ethernet ICs, co-processors, and components on SOMs. Please contact Logic for potential reference designs before selecting your peripherals.

5 System Integration

5.1 Custom Configuration

The OMAP-L138 SOM-M1 was designed to meet multiple applications for users with specific design and budget requirements. As a result, this SOM supports a variety of embedded operating systems, flexible mDDR and SPI flash memory footprints, and other hardware configurations. If your application needs require unique hardware or software configurations, please contact Logic Sales about custom SOMs available in production volumes: product.sales@logicpd.com.

5.2 Resets

The OMAP-L138 SOM-M1 has a reset input (MSTR_nRST) and a reset output (RESETOUTn). External devices use MSTR_nRST to assert reset to the product. The OMAP-L138 SOM-M1 uses RESETOUTn to indicate to other devices that the SOM is in reset.

5.2.1 Master Reset (MSTR_nRST)—Reset Input

Logic suggests that custom designs implementing the OMAP-L138 SOM-M1 use the MSTR_nRST signal as the “pin-hole” reset used in commercial embedded systems. The MSTR_nRST triggers a power-on-reset event to the OMAP-L138 processor and resets the entire CPU.

IMPORTANT NOTE: Any custom reset circuit design should guard the assertion of the reset lines during a low power state so as to prevent power-up in a low or bad power condition. (Powering up in a low or bad power condition will cause data corruption and, possibly, temporary system lockup). See the “Power Management” section of this document for further details. A low pulse on the MSTR_nRST signal will cause a system-wide reset.

Low Pulse on MSTR_nRST Signal:

A low pulse on the MSTR_nRST signal, asserted by an external source (for example, the reset button on the custom design application) will bring MSTR_nRST low until the assertion source is de-asserted. There is no delay beyond the de-assertion of the external MSTR_nRST signal source, so the custom design must ensure that the assertion time is sufficient for all related peripherals.

Logic suggests that for any external assertion source that triggers the MSTR_nRST signal, analog or digital, de-bouncing should be used to generate a clean, one-shot reset signal.

5.2.2 SOM Reset (RESETOUTn)—Reset output

All hardware peripherals should connect their hardware-reset pin to the RESETOUTn signal on the expansion connector. Internally, all OMAP-L138 SOM-M1 peripheral hardware reset pins are connected to the RESET_nOUT net.

If the output of the onboard voltage-monitoring circuit is asserted (active low), the user can expect to lose information stored in RAM. The data loss occurs because the CPU is reset to its reset defaults.

5.3 Interrupts

The OMAP-L138 interrupt controller allows either the ARM or DSP core to enable, disable, trigger, or service all interrupts. Most external GPIO signals can also be configured as interrupt inputs by configuring their pin control registers. Logic BSPs setup and process all onboard system and external SOM interrupt sources. Refer to TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides for further information on using interrupts.

5.4 JTAG Debugger Interface

The JTAG connection on the OMAP-L138 allows recovery of corrupted flash memory, real-time application debug, and DSP development. There are several third-party JTAG debuggers available for TI microcontrollers. The following signals make up the JTAG interface to the OMAP-L138 processor: TDI, TMS, TCK, TDO, nTRST, RTCK, EMU0, EMU1, and MSTR_nRST (MSTR_nRST is only required for some JTAG tools; see the JTAG tool documentation for exact pinout). These signals should interface directly to a 14 or 20-pin 0.1" through-hole connector, as shown on Logic's *OMAP-L138 Baseboard Schematic*.

IMPORTANT NOTE: When laying out the JTAG connector, realize that it may not be numbered as a standard 14 or 20-pin 0.1" insulation displacement connector (IDC) through-hole connector. See the *OMAP-L138 Baseboard Schematic* for further details. Each JTAG tool vendor may define the IDC connector pin-out differently.

5.5 Power Management

5.5.1 System Power Supplies

In order to ensure a flexible design, the OMAP-L138 SOM-M1 has the following power areas: MAIN_BATT_IN, 5V, RTC_BATT. All power areas are inputs to the SOM. The module also provides output reference voltage 3.3V_or_1.8V. 3.3V_or_1.8V is an output from the SOM, and should only be used as a reference voltage input to level shifting devices on baseboard designs.

IMPORTANT NOTE: If USB0_VBUS is powered externally it will power the SOM, even if MAIN_BATT_IN and 5V are disconnected. Additionally, USB0_VBUS can charge MAIN_BATT_IN. Please refer to the *TPS65070 Datasheet* for more information.

5.5.1.1 5V

The 5V input is the main source of power for the OMAP-L138 SOM-M1. If power is present at the 5V input, the TPS65070 PMIC will preferentially select this power source over all other sources. If appropriate voltage is applied to the 5V input, the TPS65070 PMIC and OMAP-L138 processor will immediately start up and run. 5V input is capable of charging MAIN_BATT_IN.

For startup, acceptable 5V input range is: $3.6V < 5V \text{ input} < 5.8V$

At runtime, 5V range is: $UVLO < 5V \text{ input} < 5.8V$

UVLO = UnderVoltage LockOut

UVLO = 3.0V (default), $2.8V < UVLO < 3.25V$ (programmable)

5.5.1.2 USB0_VBUS

USB0_VBUS is an optional power source for the OMAP-L138 SOM-M1. If power is present at the USB0_VBUS input, the TPS65070 PMIC will preferentially select this source over

MAIN_BATT_IN. If appropriate voltage is applied to the USB0_VBUS input, the TPS65070 PMIC and OMAP-L138 processor will immediately start up and run. The USB0_VBUS input is capable of charging MAIN_BATT_IN.

5.5.1.3 MAIN_BATT_IN

The MAIN_BATT_IN input is designed to be connected to a typical single lithium-ion battery. The TPS65070 PMIC will only power the SOM from MAIN_BATT_IN if power is not present at 5V or USB0_VBUS inputs. If appropriate voltage is applied to the MAIN_BATT_IN input, the TPS65070 PMIC and OMAP-L138 processor will NOT immediately start up and run; a momentary low signal is also required on the PMIC_PB_IN pin. The TPS65070 PMIC is capable of charging MAIN_BATT_IN from either the 5V input or the USB0_VBUS input.

For startup, MAIN_BATT_IN range is: $3.6V < \text{MAIN_BATT_IN} < 4.2V$

At runtime, MAIN_BATT_IN range is: $\text{UVLO} < \text{MAIN_BATT_IN} < 4.2V$

UVLO = UnderVoltage LockOut

UVLO = 3.0V (default), $2.8V < \text{UVLO} < 3.25V$ (programmable)

IMPORTANT NOTES:

Though UVLO may be set as low as 2.8V, not all OMAP-L138 SOM-M1 circuits are capable of 2.8V operation. The SOM contains an internal 3.3V power rail, and devices connected to this rail may have dropout voltages much greater than UVLO. See Section 3.2 for the recommended range of input voltages.

Before designing a system which powers the OMAP-L138 SOM-M1 from MAIN_BATT_IN, the user should first review the following documents: *TPS65070 Datasheet*, *OMAP-L138 SOM-M1 Schematic*, and *OMAP-L138 Baseboard Schematic*.

5.5.1.4 VRTC_IN

The VRTC_IN power rail is used to power the onboard RTC module. Always power this rail to maintain the clock of the product. A lithium-ion coin cell typically supplies power to this rail.

5.5.2 Dual Voltage I/O

The OMAP-L138 processor and OMAP-L138 SOM-M1 uniquely support dual-voltage I/O. The user may select an operating voltage of either 1.8V or 3.3V through "IO_VOLTAGE_SEL" J1.37. For 3.3V operation, J1.37 should be left unconnected. For 1.8V operation, J1.37 should be tied directly to GND.

5.5.3 System Power Management

Good power management design is important in any system development and embedded system design is no exception. In embedded system design, power management is typically one of the most complicated areas due to the dramatic effect it has on product cost, performance, usability, and overall customer satisfaction. Many factors affect a power-efficient hardware design: power supply selection (efficiency), clocking design, IC and component selection, etc. The OMAP-L138 SOM-M1 was designed with these aspects in mind while also providing maximum flexibility in software and system integration.

On the OMAP-L138 there are many different software configurations that drastically affect power consumption: microcontroller core clock frequency, bus clock frequency, peripheral clocks, bus

modes, power management states; peripheral power states and modes; product user scenarios; interrupt handling; and display settings (resolution, backlight, refresh, bits per pixel, etc). These settings are typically initialized in the startup software routines and may be modified later in the operating system and application software. Information for these items can be found in the appropriate documents such as the *U-Boot User's Manual*, TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides, *TPS65070 Datasheet*, and Logic's *OMAP-L138 SOM-M1 Schematic*.

5.5.4 Microcontroller

The OMAP-L138 processor's power management scheme was designed for ultra-low power, so naturally the static and dynamic power consumption has very flexible controls allowing designers to configure the processor to minimize end-product power consumption. Most peripheral modules can be powered on/off individually, and the core(s) can enter various levels of standby/sleep. To implement a low-power system, users should review TI's *OMAP-L138 Low-Power Applications Processor Datasheet* and User Guides, *TPS65070 Datasheet*, and Logic's *OMAP-L138 SOM-M1 Schematic*.

5.6 ESD Considerations

The OMAP-L138 SOM-M1 was designed to interface to a customer's peripheral board, while remaining low cost and adaptable to many different applications. The SOM does not provide any onboard ESD protection circuitry—this must be provided by the product it is used in. Logic has extensive experience in designing products with ESD requirements. Please contact Logic if you need any assistance in ESD design considerations.

6 Memory & I/O Mapping

OMAP-L138 chip select signals are described listed below:

| Chip Select | Device/Feature | Notes |
|---------------|------------------|---|
| SPI0_SCS[0:5] | Not Available | MDIO/MII comm. interfaces on SOM |
| SPI1_SCS[0] | SPI Flash (boot) | LCD Backlight PWM on dev kit |
| SPI1_SCS[1] | | LCD Backlight Power on dev kit |
| SPI1_SCS[2:3] | | Available for use by an off-board external device |
| SPI1_SCS[4] | | UART TXD on dev kit |
| SPI1_SCS[5] | | UART RXD on dev kit |
| SPI1_SCS[6] | Not Available | I2C0 is used extensively for configuration/control on both the SOM and dev. kit |
| SPI1_SCS[7] | Not Available | I2C0 is used extensively for configuration/control on both the SOM and dev. kit |
| EMA_CS[0] | | Available for use by an off-board external device |
| EMA_CS[2:5] | | Available for use by an off-board external device |
| UHPI_HCS | | Available for use by an off-board external device |

7 Pin Descriptions & Functions

SOM Net Name: This is the name used in Logic's *OMAP-L138 SOM-M1 Schematics*.

Processor Name: This is the name used TI's *OMAP-L138 Low-Power Applications Processor Datasheet*.

I/O: This indicates the default pin configuration after booting U-Boot. Most pins can be reconfigured as either input or output. Consult Logic's *OMAP-L138 SOM-M1 Schematics* and TI's *OMAP-L138 Low-Power Applications Processor Datasheet* for more information.

Description: If a pull-up or pull-down resistor is present on the OMAP-L138 SOM-M1, it will be noted here. Special usage tips and cautions will be noted here. Consult Logic's *OMAP-L138 SOM-M1 Schematics* and TI's *OMAP-L138 Low-Power Applications Processor Datasheet* for more information.

7.1 J1 Connector 100-Pin Descriptions

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|----------------|---|------|------------------------------|---|
| 1 | uP_VPIF_DOUT8 | VP_DOUT[8]/ LCD_D[8]/ UPP_XD[0]/ GP7[0]/ BOOT[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G3 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 2 | uP_VPIF_DOUT0 | VP_DOUT[0]/ LCD_D[0]/ UPP_XD[8]/ GP7[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_B1 data bit when outputting RGB565 data to an RGB666 display. |
| 3 | uP_VPIF_DOUT9 | VP_DOUT[9]/ LCD_D[9]/ UPP_XD[1]/ GP7[1]/ BOOT[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G4 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 4 | uP_VPIF_DOUT1 | VP_DOUT[1]/ LCD_D[1]/ UPP_XD[9]/ GP7[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_B2 data bit when outputting RGB565 data to an RGB666 display. |
| 5 | uP_VPIF_DOUT10 | VP_DOUT[10]/ LCD_D[10]/ UPP_XD[2]/ GP7[2]/ BOOT[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G5 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-up on SOM. Used to latch boot mode at startup (see Note 2). |
| 6 | uP_VPIF_DOUT2 | VP_DOUT[2]/ LCD_D[2]/ UPP_XD[10]/ GP7[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_B3 data bit when outputting RGB565 data to an RGB666 display. |
| 7 | uP_VPIF_DOUT11 | VP_DOUT[11]/ LCD_D[11]/ UPP_XD[3]/ GP7[3]/ BOOT[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_R1 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-up on SOM. Used to latch boot mode at startup (see Note 2). |
| 8 | uP_VPIF_DOUT3 | VP_DOUT[3]/ LCD_D[3]/ UPP_XD[11]/ GP7[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_B4 data bit when outputting RGB565 data to an RGB666 display. |

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|-----------------------|---|------|------------------------------|--|
| 9 | uP_VPIF_DOUT12 | VP_DOUT[12]/ LCD_D[12]/ UPP_XD[4]/ GP7[4]/ BOOT[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_R2 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 10 | uP_VPIF_DOUT4 | VP_DOUT[4]/ LCD_D[4]/ UPP_XD[12]/ GP7[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_B5 data bit when outputting RGB565 data to an RGB666 display. Notice that LCD_B0 is omitted; LCD_B5 (Blue MSB) is also connected to LCD_B0 (Blue LSB) when driving an 18 bit display with 16 bits. |
| 11 | uP_VPIF_DOUT13 | VP_DOUT[13]/ LCD_D[13]/ UPP_XD[5]/ GP7[5]/ BOOT[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_R3 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 12 | uP_VPIF_DOUT5 | VP_DOUT[5]/ LCD_D[5]/ UPP_XD[13]/ GP7[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G0 data bit when outputting RGB565 data to an RGB666 display. |
| 13 | uP_VPIF_DOUT14 | VP_DOUT[14]/ LCD_D[14]/ UPP_XD[6]/ GP7[6]/ BOOT[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_R4 data bit when outputting RGB565 data to an RGB666 display. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 14 | uP_VPIF_DOUT6 | VP_DOUT[6]/ LCD_D[6]/ UPP_XD[14]/ GP7[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G1 data bit when outputting RGB565 data to an RGB666 display. |
| 15 | uP_VPIF_DOUT15 | VP_DOUT[15]/ LCD_D[15]/ UPP_XD[7]/ GP7[7]/ BOOT[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_R5 data bit when outputting RGB565 data to an RGB666 display. Notice that LCD_R0 is omitted; LCD_R5 (Red MSB) is also connected to LCD_R0 (Red LSB) when driving an 18 bit display with 16 bits. 4.7k pull-down on SOM. Used to latch boot mode at startup (see Note 2). |
| 16 | uP_VPIF_DOUT7 | VP_DOUT[7]/ LCD_D[7]/ UPP_XD[15]/ GP7[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | LCD_G2 data bit when outputting RGB565 data to an RGB666 display. |
| 17 | uP_LCD_HSYNC | MMCS1_DAT[5]/ LCD_HSYNC/ GP8[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 18 | uP_LCD_PCLK | MMCS1_DAT[7]/ LCD_PCLK/ GP8[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 19 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 20 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 21 | uP_LCD_VSYNC | MMCS1_DAT[4]/ LCD_VSYNC/ GP8[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 22 | uP_LCD_MCLK | MMCS1_DAT[6]/ LCD_MCLK/ GP8[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 23 | uP_LCD_AC_ENB_C Sn | LCD_AC_ENB_C S/ GP6[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|-----------------|--|------|------------------------------|---|
| 24 | uP_VPIF_CLKIN0 | VP_CLKIN0/ UHPI_HCS/ GP6[7]/ UPP_2xTXCLK | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 25 | uP_USB0_DRVVBUS | USB0_DRVVBUS | O | — | — |
| 26 | uP_VPIF_DIN14 | VP_DIN[14]_ HSYNC/ UHPI_HD[6]/ UPP_CHA_D[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 27 | uP_VPIF_CLKO3 | VP_CLKOUT3/ GP6[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 28 | uP_VPIF_DIN15 | VP_DIN[15]_ VSYNC/ UHPI_HD[7]/ UPP_CHA_D[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 29 | uP_RESETh | RESET | I | 3.3V or 1.8V (see Note 4) | 4.7k pull-up on SOM. Also connected to PGOOD on TPS65070 PMIC. PGOOD is an open drain output. |
| 30 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 31 | uP_NMIh | NMI | I | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. Also connected to INTn on TPS65070 PMIC. INTn is an open drain output. |
| 32 | uP_VPIF_DIN13 | VP_DIN[13]_ FIELD/ UHPI_HD[5]/ UPP_CHA_D[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 33 | PMIC_PB_IN | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. See Section 5.5.1.3. Buffered version of this input can be read on OMAP-L138 pin EMA_RAS / GPIO2[5] |
| 34 | uP_VPIF_DIN12 | VP_DIN[12]/ UHPI_HD[4]/ UPP_CHA_D[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 35 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 36 | uP_VPIF_DIN11 | VP_DIN[11]/ UHPI_HD[3]/ UPP_CHA_D[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 37 | IO_VOLTAGE_SEL | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. See Section 5.5.2 |
| 38 | uP_VPIF_DIN10 | VP_DIN[10]/ UHPI_HD[2]/ UPP_CHA_D[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 39 | uP_EPWM0_TZ[0] | AXR15/ EPWM0TZ[0]/ ECAP2_APWM2/ GP0[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 40 | uP_VPIF_DIN9 | VP_DIN[9]/UHPI_ HD[1]/UPP_CHA_ D[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 41 | uP_EPWM1_TZ[0] | AXR7/ EPWM1TZ[0]/ GP1[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|----------------|--|------|---------------------------|--|
| 42 | uP_VPIF_DIN8 | VP_DIN[8]/UHPI_HD[0]/UPP_CHA_D[0]/GP6[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 43 | SATA_RXP | SATA_RXP | I | — | — |
| 44 | uP_SPI0_SCSn4 | SPI0_SCS[4]/UART0_TXD/GP8[3]/MII_RXD[2] | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-down on SOM. |
| 45 | SATA_RXN | SATA_RXN | I | — | — |
| 46 | uP_SPI0_SCSn3 | SPI0_SCS[3]/UART0_CTS // GP8[2]/MII_RXD[1]/SATA_MP_SWITC H | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-up on SOM. |
| 47 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 48 | uP_SPI0_SCSn2 | SPI0_SCS[2]/UART0_RTS/GP8[1]/MII_RXD[0]/SATA_CP_DET | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-up on SOM. |
| 49 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 50 | uP_SPI0_SCSn5 | SPI0_SCS[5]/UART0_RXD/GP8[4]/MII_RXD[3] | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-down on SOM. |
| 51 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 52 | uP_UART2_RTSn | AMUTE/UART2_RTS/GP0[9] | O | 3.3V or 1.8V (see Note 1) | — |
| 53 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 54 | uP_UART2_CTSn | RSVD/RTC_ALARM/UART2_CTS/GP0[8]/DEEPSLEEP | I | 3.3V or 1.8V (see Note 1) | — |
| 55 | SATA_TXN | SATA_TXN | O | — | — |
| 56 | uP_EMIFA_A15 | EMA_A[15]/MMCSD0_DAT[6]/GP5[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 57 | SATA_TXP | SATA_TXP | O | — | — |
| 58 | uP_EMIFA_A14 | EMA_A[14]/MMCSD0_DAT[7]/GP5[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 59 | uP_EMIFA_A21 | EMA_A[21]/MMCSD0_DAT[0]/GP4[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 60 | uP_UPP_CH0_CLK | MMCSD1_DAT[0]/UPP_CHB_CLK/GP8[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 61 | uP_EMIFA_A20 | EMA_A[20]/MMCSD0_DAT[1]/GP4[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|-------------------|---|------|------------------------------|---|
| 62 | uP_VPIF_CLKIN3 | VP_CLKIN3/ MMCSD1_DAT[1]/ GP6[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 63 | uP_EMIFA_A19 | EMA_A[19]/ MMCSD0_DAT[2]/ GP4[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 64 | uP_VPIF_CLKO2 | VP_CLKOUT2/ MMCSD1_DAT2/ GP6[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 65 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | I/O Voltage Output from SOM. Do not use this as a general purpose power source. Use this pin to power level shifters etc. |
| 66 | uP_VPIF_CLKIN2 | VP_CLKIN2/ MMCSD1_DAT[3]/ GP6[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 67 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | I/O Voltage Output from SOM. Do not use this as a general purpose power source. Use this pin to power level shifters etc. |
| 68 | TOUCH_X1 | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. Touch Right (X+) Processor reads via I2C |
| 69 | uP_EMIFA_A18 | EMA_A[18]/ MMCSD0_DAT[3]/ GP4[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 70 | TOUCH_X2 | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. Touch Left (X-) Processor reads via I2C |
| 71 | uP_EMIFA_A17 | EMA_A[17]/ MMCSD0_DAT[4]/ GP4[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 72 | TOUCH_Y1 | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. Touch Up (Y+) Processor reads via I2C |
| 73 | uP_EMIFA_A16 | EMA_A[16]/ MMCSD0_DAT[5]/ GP4[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 74 | TOUCH_Y2 | — | I/O | — | Input to TPS65070 PMIC, not OMAP-L138. Touch Down (Y-) Processor reads via I2C |
| 75 | uP_EMIFA_A22 | EMA_A[22]/ MMCSD0_CMD/ GP4[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 76 | uP_UPP_CH0_ENABLE | MMCSD1_CMD/ UPP_CHB_ENABLE/ GP8[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 77 | uP_EMIFA_A23 | EMA_A[23]/ MMCSD0_CLK/ GP4[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 78 | uP_UPP_CH0_START | MMCSD1_CLK/ UPP_CHB_START/ GP8[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 79 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 80 | DGND | — | I | GND | Ground. Connect to digital ground. |

| J1 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|---------------|--|------|------------------------------|--|
| 81 | uP_USB1_DM | USB1_DM | I/O | (see Note 3) | 24.9 ohm series R on SOM. 15k pull-down on SOM. |
| 82 | uP_USB0_DM | USB0_DM | I/O | (see Note 3) | — |
| 83 | uP_USB1_DP | USB1_DP | I/O | (see Note 3) | 24.9 ohm series R on SOM. 15k pull-down on SOM. |
| 84 | uP_USB0_DP | USB0_DP | I/O | (see Note 3) | — |
| 85 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 86 | uP_USB0_ID | USB0_ID | I | +5V or GND | — |
| 87 | USB_VBUS | USB0_VBUS | I | +5V or GND | Also connects to TPS65070 PMIC. (see Note 4) |
| 88 | USB_VBUS | USB0_VBUS | I | +5V or GND | — |
| 89 | uP_UART1_CTSn | AHCLKX/ USB_REFCLKIN/ UART1_CTS/ GP0[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM |
| 90 | 5V_IN | — | I | 5V | — |
| 91 | uP_UART1_RTSn | AHCLKR/ UART1_RTS/ GP0[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM |
| 92 | 5V_IN | — | I | 5V | — |
| 93 | uP_SPI1_SCSn2 | SPI1_SCS[2]/ UART1_TXD/ SATA_CP_POD/ GP1[0] | O | 3.3V or 1.8V (see Note 1) | — |
| 94 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 95 | uP_SPI1_SCSn3 | SPI1_SCS[3]/ UART1_RXD/ SATA_LED/ GP1[1] | O | 3.3V or 1.8V (see Note 1) | — |
| 96 | 5V_IN | — | I | 5V | — |
| 97 | uP_SPI1_SCSn4 | SPI1_SCS[4]/ UART2_TXD/ I2C1_SDA/ GP1[2] | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |
| 98 | 5V_IN | — | I | 5V | — |
| 99 | uP_SPI1_SCSn5 | SPI1_SCS[5]/ UART2_RXD/ I2C1_SCL/ GP1[3] | I | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |
| 100 | DGND | — | I | GND | Ground. Connect to digital ground. |

Note 1: Most OMAP-L138 SOM-M1 I/O pins are dual-voltage capable; that is, the SOM I/O pins may be configured to operate at 3.3V or 1.8V. The desired I/O voltage is set via J1.37. See Section 5.5.2 for more information.

Note 2: At startup, the boot mode is determined by sampling BOOT[0:7] (i.e., LCD_D[8:15]). Resistors on the SOM pull these pins to a default value. User boards may select alternate boot modes by pulling selected pins opposite their default value; to do this, the user's board must use resistors of much lower impedance than those used on the SOM. User boards must ensure that other circuits do not drive or load down these pins at startup. Driving/loading these pins at startup may cause the processor to latch an incorrect boot mode. For compatibility with the SOM-M1 form factor, BOOT[1:4] (LCD_D[9,10,11,12] or J1.3,5,7,9) are connected to BOOTBIT[1:4] (J3.2,4,12,14) through zero ohm resistors.

Note 3: USB voltage levels follow the USB specification and depend on the USB operating speed. Please see the USB specification for more information.

Note 4: USB0_VBUS can be used to power the SOM. Please see the *TPS65070 Datasheet* for more information.

7.2 J2 Connector 100-Pin Descriptions

| J2 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|----------------|------------------------|------|------------------------------|--|
| 1 | uP_EMIFA_D7 | EMA_D[7]/ GP4[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 2 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 3 | uP_EMIFA_D8 | EMA_D[8]/ GP3[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 4 | uP_EMIFA_WAIT1 | EMA_WAIT[1]/ GP2[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM |
| 5 | uP_EMIFA_D9 | EMA_D[9]/ GP3[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 6 | uP_EMIFA_WAIT0 | EMA_WAIT[0]/ GP3[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM |
| 7 | uP_EMIFA_D10 | EMA_D[10]/ GP3[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 8 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 9 | uP_EMIFA_D11 | EMA_D[11]/ GP3[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 10 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 11 | uP_EMIFA_D12 | EMA_D[12]/ GP3[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 12 | uP_EMIFA_WEn | EMA_WE/ GP3[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 13 | uP_EMIFA_D13 | EMA_D[13]/ GP3[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 14 | uP_EMIFA_OEn | EMA_OE/ GP3[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 15 | uP_EMIFA_D14 | EMA_D[14]/ GP3[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 16 | uP_EMIFA_RnW | EMA_A_RW / GP3[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |
| 17 | uP_EMIFA_D15 | EMA_D[15]/ GP3[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 18 | uP_EMIFA_CLK | EMA_CLK/ GP2[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 19 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 20 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 21 | uP_EMIFA_A0 | EMA_A[0]/ GP5[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 22 | uP_EMIFA_CSn5 | EMA_CS[5]/ GP3[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 23 | uP_EMIFA_A1 | EMA_A[1]/ GP5[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 24 | uP_EMIFA_CSn4 | EMA_CS[4]/ GP3[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |

| J2 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|---------------|-----------------------|------|------------------------------|---|
| 25 | uP_EMIFA_A2 | EMA_A[2]/ GP5[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 26 | uP_EMIFA_CSn3 | EMA_CS[3]/ GP3[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 27 | uP_EMIFA_A3 | EMA_A[3]/ GP5[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 28 | uP_EMIFA_CSn2 | EMA_CS[2]/ GP3[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 29 | uP_EMIFA_A4 | EMA_A[4]/ GP5[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 30 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 31 | uP_EMIFA_A5 | EMA_A[5]/ GP5[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 32 | uP_EMIFA_CSn0 | EMA_CS[0]/ GP2[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 33 | uP_EMIFA_A6 | EMA_A[6]/ GP5[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 34 | uP_EMIFA_D0 | EMA_D[0]/ GP4[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 35 | uP_EMIFA_A7 | EMA_A7/ GP5[7] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 36 | uP_EMIFA_D1 | EMA_D[1]/ GP4[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 37 | uP_EMIFA_A8 | EMA_A[8]/ GP5[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 38 | uP_EMIFA_D2 | EMA_D[2]/ GP4[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 39 | uP_EMIFA_A9 | EMA_A[9]/ GP5[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 40 | uP_EMIFA_D3 | EMA_D[3]/ GP4[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 41 | uP_EMIFA_A10 | EMA_A[10]/ GP5[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 42 | uP_EMIFA_D4 | EMA_D[4]/ GP4[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 43 | uP_EMIFA_A11 | EMA_A[11]/ GP5[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 44 | uP_EMIFA_D5 | EMA_D[5]/ GP4[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 45 | uP_EMIFA_A12 | EMA_A[12]/ GP5[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 46 | uP_EMIFA_D6 | EMA_D[6]/ GP4[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 47 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 48 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 49 | MAIN_BATT_IN | — | I/O | — | Designed for a standard lithium battery. See Section 5.5.1.3 |
| 50 | MAIN_BATT_IN | — | I/O | — | Designed for a standard lithium battery. See Section 5.5.1.3 |
| 51 | MAIN_BATT_IN | — | I/O | — | Designed for a standard lithium battery. See Section 5.5.1.3 |

| J2 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|---------------------|--|------|------------------------------|---|
| 52 | MAIN_BATT_IN | — | I/O | — | Designed for a standard lithium battery. See Section 5.5.1.3 |
| 53 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 54 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 55 | uP_EMIFA_A13 | EMA_A[13]/ GP5[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 56 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 57 | ETHER_SPEED_LED | — | O | — | Connect cathode of Ethernet Speed LED |
| 58 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 59 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 60 | uP_SPI1_SCSn6 | SPI1_SCS[6]/ I2C0_SDA/ TM64P3_OUT12/ GP1[4] | I/O | 3.3V or 1.8V (see Note 1) | I2C0 bus is used for communication between the OMAP-L138 processor and the TPS65070 PMIC. 4.7k pull-up on SOM. |
| 61 | RFU | — | — | NA | Reserved for future use. Do not connect. |
| 62 | uP_SPI1_SCSn7 | SPI1_SCS[7]/ I2C0_SCL/ TM64P2_OUT12/ GP1[15] | O | 3.3V or 1.8V (see Note 1) | I2C0 bus is used for communication between the OMAP-L138 processor and the TPS65070 PMIC. 4.7k pull-up on SOM. |
| 63 | ETHER_LINK_ACT_LEDn | — | O | — | Connect to cathode of Ethernet Act. LED 4.7k pull-up on SOM. |
| 64 | VRTC_IN | — | I | — | — |
| 65 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | — |
| 66 | uP_MCBSP0_CLKR | AXR6/ CLKR0/ GP1[14]/ MII_TXEN | O | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 22 ohm series R on SOM. |
| 67 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | — |
| 68 | uP_MCBSP0_CLKS | AXR0/ ECAPO_APWM0/ GP8[7]/ MII_TXD[0]/ CLKS0 | O | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 22 ohm series R on SOM. |
| 69 | uP_SPI1_ENAn | SPI1_ENA/ GP2[12] | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |
| 70 | uP_MCBSP0_FSX | AXR3/ FSX0/ GP1[11]/ MII_TXD[3] | O | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. |
| 71 | ETHER_TX+ | — | O | — | 49.9 ohm pull-up on SOM. |
| 72 | uP_MCBSP0_DR | AXR2/ DR0/ GP2[10]/ MII_TXD[2] | O | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. |
| 73 | ETHER_TX- | — | O | — | 49.9 ohm pull-up on SOM. |
| 74 | uP_MCBSP0_DX | AXR1/ DX0/ GP1[19]/ MII_TXD[1] | O | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. |
| 75 | ETHER_RX+ | — | I | — | 49.9 ohm pull-up on SOM. |
| 76 | uP_MCBSP0_FSR | AXR4/ FSR0/ GP1[12]/ MII_COL | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-up on SOM. |

| J2 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|----------------|--|------|------------------------------|--|
| 77 | ETHER_RX- | — | I | — | 49.9 ohm pull-up on SOM. |
| 78 | uP_MCBSP0_CLKX | AXR5/ CLKX0/ GP1[13]/ MII_TXCLK | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 22 ohm series R on SOM. |
| 79 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 80 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 81 | uP_SPI0_CLK | SPI0_CLK/ EPWM0A/ GP1[8]/ MII_RXCLK/ | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 22 ohm series R on SOM. 4.7k pull-down on SOM. |
| 82 | uP_MCBSP1_CLKX | AXR13/ CLKX1/ GP0[5] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 83 | uP_SPI0_SOMI | SPI0_SOMI/ EPWMSYNCI/ GP8[6]/ MII_RXER | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. 4.7k pull-down on SOM. |
| 84 | uP_MCBSP1_FSX | AXR11/ FSX1/ GP0[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 85 | uP_SPI0_SIMO | SPI0_SIMO/ EPWMSYNCO/ GP8[5]/ MII_CRS | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. |
| 86 | uP_MCBSP1_DX | AXR9/ DX1/ GP0[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 87 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 88 | uP_MCBSP1_DR | AXR10/ DR1/ GP0[2] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 89 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 90 | uP_MCBSP1_CLKR | AXR14/ CLKR1/ GP0[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 91 | uP_EMIFA_BA0 | EMA_BA[0]/ GP2[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 92 | uP_MCBSP1_CLKS | AXR8/ CLKS1/ ECAP1_APWM1/ GP0[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 93 | uP_EMIFA_BA1 | EMA_BA[1]/ GP2[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 94 | uP_MCBSP1_FSR | AXR12/ FSR1/ GP0[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 95 | uP_SPI0_ENAn | SPI0_ENA/ EPWM0B/ MII_RXDV | I | 3.3V or 1.8V (see Note 1) | MII bus is used to communicate between the OMAP-L138 processor and LAN8710 Ethernet PHY on the SOM. |
| 96 | uP_SPI1_CLK | SPI1_CLK/ GP2[13] | O | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. 4.7k pull-up on SOM. |
| 97 | uP_SPI1_SCSn1 | SPI1_SCS[1]/ EPWM1A/ GP2[15]/ TM64P2_IN12 | O | 3.3V or 1.8V (see Note 1) | — |
| 98 | uP_SPI1_SOMI | SPI1_SOMI/ GP2[11] | I | 3.3V or 1.8V (see Note 1) | — |

| J2 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|---------------|--|-----|------------------------------|----------------------|
| 99 | uP_SPI1_SCSn0 | SPI1_SCS[0]/ EPWM1B/ GP2[14]/ TM64P3_IN12 | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |
| 100 | uP_SPI1_SIMO | SPI1_SIMO/ GP2[10] | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM. |

Note 1: Most OMAP-L138 SOM-M1 I/O pins are dual-voltage capable; that is, the SOM I/O pins may be configured to operate at 3.3V or 1.8V. The desired I/O voltage is set via J1.37. See Section 5.5.2 for more information.

7.3 J3 Connector 100-Pin Descriptions

| J3 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|------------------|----------------------------------|------|------------------------------|--|
| 1 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 2 | BOOTBIT2 | — | NA | 3.3V or 1.8V (see Note 1) | Do not connect. Connected to J1.5 via zero ohm res. on SOM. |
| 3 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 4 | BOOTBIT4 | — | NA | 3.3V or 1.8V (see Note 1) | Do not connect. Connected to J1.9 via zero ohm res. on SOM. |
| 5 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 6 | BATT_HDQ | EMA_WEN_DQM[0]/ GP2[3] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 7 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 8 | RFU (PM_I2C_SCL) | — | NA | — | Do not connect. |
| 9 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 10 | RFU (PM_I2C_SDA) | — | NA | — | Do not connect. |
| 11 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 12 | BOOTBIT1 | — | NA | 3.3V or 1.8V (see Note 1) | Do not connect. Connected to J1.3 via zero ohm res. on SOM. |
| 13 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 14 | BOOTBIT3 | — | NA | 3.3V or 1.8V (see Note 1) | Do not connect. Connected to J1.7 via zero ohm res. on SOM. |
| 15 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 16 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 17 | BATT_TS | — | I/O | — | Sense line for thermal resistor in battery pack. |
| 18 | uP_OBSCLK | CLKOUT/ UHPI_HDS2/ GP6[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 19 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 20 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 21 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 22 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 23 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 24 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 25 | RFU | — | NA | NA | Reserved for future use. Do not connect. |

| J3 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|------------------|--|------|------------------------------|--|
| 26 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 27 | uP_SPI0_SCSn0 | SPI0_SCS[0]/ TM64P1_OUT12/ GP1[6]/ MDIO_D/ TM64P1_IN12 | I/O | 3.3V or 1.8V (see Note 1) | MDIO bus is used to communicate between OMAP-L138 and LAN8710 Ethernet PHY on SOM. |
| 28 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 29 | uP_SPI0_SCSn1 | SPI0_SCS[1]/ TM64P0_OUT12/ GP1[7]/ MDIO_CLK/ TM64P0_IN12 | O | 3.3V or 1.8V (see Note 1) | MDIO bus is used to communicate between OMAP-L138 and LAN8710 Ethernet PHY on SOM. |
| 30 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 31 | uP_VPIF_DIN7 | VP_DIN[7]/ UHPI_HD[15]/ UPP_CHA_D[15]/ RMII_TXD[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 32 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 33 | uP_VPIF_DIN5 | VP_DIN[5]/ UHPI_HD[13]/ UPP_CHA_D[13]/ RMII_TXEN | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 34 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 35 | uP_VPIF_DIN6 | VP_DIN[6]/UHPI_HD[14]/UPP_CHA_D[14]/RMII_TXD[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 36 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 37 | uP_VPIF_DIN2 | VP_DIN[2]/ UHPI_HD[10]/ UPP_CHA_D[10]/ RMII_RXER | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 38 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 39 | uP_VPIF_DIN0 | VP_DIN[0]/ UHPI_HD[8]/ UPP_CHA_D[8]/ RMII_CRS_DV | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 40 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 41 | uP_VPIF_DIN4 | VP_DIN[4]/ UHPI_HD[12]/ UPP_CHA_D[12]/ RMII_RXD[1] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 42 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 43 | uP_VPIF_DIN3 | VP_DIN[3]/ UHPI_HD[11]/ UPP_CHA_D[11]/ RMII_RXD[0] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 44 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 45 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 46 | uP_UPP_CH1_START | UHPI_HCNTL1/ UPP_CHA_START/ GP6[10] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 47 | USB1_PWR_EN | EMA_CAS/ GP2[4] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |

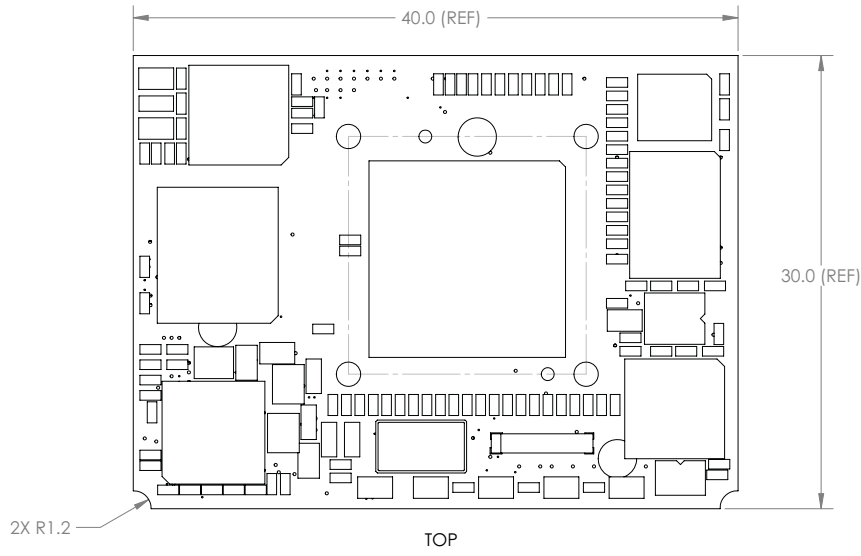
| J3 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|-------------------|---|------|------------------------------|--|
| 48 | uP_VPIF_CLKIN1 | VP_CLKIN1/ UHPI_HDS1/ GP6[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 49 | uP_VPIF_DIN1 | VP_DIN[1]/ UHPI_HD[9]/ UPP_CHA_D[9]/ RMII_MHZ_50_CLK | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 50 | uP_UPP_CH1_CLK | UHPI_HCNTL0/ UPP_CHA_CLK/ GP6[11] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 51 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 52 | uP_UPP_CH1_ENABLE | UHPI_HHWIL/ UPP_CHA_ENABLE/ GP6[9] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 53 | uP_McASP_CLKX | ACLKX/ GP0[14] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 54 | uP_RESETOUTn | RESETOUT/ UHPI_HAS/ GP6[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 55 | uP_McASP_CLKR | ACLKR/ GP0[15] | Hi-Z | 3.3V or 1.8V (see Note 1) | 22 ohm series R on SOM. |
| 56 | uP_UPP_CH1_WAIT | UHPI_HRW/ UPP_CH1_WAIT/ GP6[8] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 57 | uP_McASP_FSX | AFX/ GP0[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 58 | uP_UHPI_HRDY | UHPI_HRDY/GP6[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 59 | uP_McASP_FSR | AFSR/ GP0[13] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 60 | uP_UHPI_HINTn | UHPI_HINT/GP6[12] | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 61 | BUFF_OEn | EMA_SDCKE/ GP2[6] | Hi-Z | 3.3V or 1.8V (see Note 1) | 1k pull-down on SOM. |
| 62 | uP_UPP_CH0_WAIT | UPP_CHB_WAIT/ GP8[12]/ | Hi-Z | 3.3V or 1.8V (see Note 1) | — |
| 63 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 64 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 65 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | — |
| 66 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 67 | 3.3V_or_1.8V | — | O | 3.3V or 1.8V (see Note 1) | — |
| 68 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 69 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 70 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 71 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 72 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 73 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 74 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 75 | RFU | — | NA | NA | Reserved for future use. Do not connect. |

| J3 Pin# | SOM Net Name | Processor Name | I/O | Voltage | Description |
|---------|--------------|----------------|-----|------------------------------|--|
| 76 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 77 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 78 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 79 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 80 | DGND | — | I | GND | Ground. Connect to digital ground. |
| 81 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 82 | uP_TCK | TCK | I | 3.3V or 1.8V (see Note 1) | — |
| 83 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 84 | uP_RTCK | RTCK/ GP8[0] | O | 3.3V or 1.8V (see Note 1) | — |
| 85 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 86 | uP_EMU1 | EMU1 | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM |
| 87 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 88 | uP_EMU0 | EMU0 | O | 3.3V or 1.8V (see Note 1) | 4.7k pull-up on SOM |
| 89 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 90 | uP_TDO | TDO | O | 3.3V or 1.8V (see Note 1) | — |
| 91 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 92 | uP_TDI | TDI | I | 3.3V or 1.8V (see Note 1) | — |
| 93 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 94 | uP_TMS | TMS | I | 3.3V or 1.8V (see Note 1) | — |
| 95 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 96 | uP_TRSTn | TRST | I | 3.3V or 1.8V (see Note 1) | — |
| 97 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 98 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 99 | RFU | — | NA | NA | Reserved for future use. Do not connect. |
| 100 | RFU | — | NA | NA | Reserved for future use. Do not connect. |

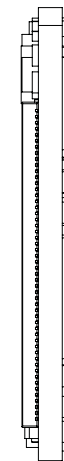
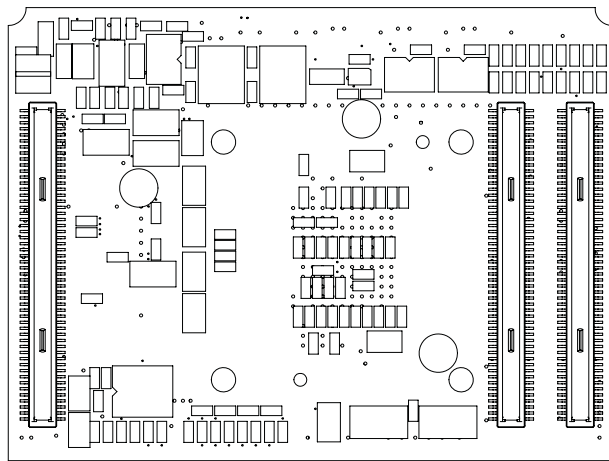
Note 1: Most OMAP-L138 SOM-M1 I/O pins are dual-voltage capable; that is, the SOM I/O pins may be configured to operate at 3.3V or 1.8V. The desired I/O voltage is set via J1.37. See Section 5.5.2 for more information.

Appendix A: SOM-M1 Mechanical Drawing

| REVISIONS | | | |
|-----------|------------|-----------------------------|----------|
| REV. | ECO NUMBER | DESCRIPTION | DATE |
| A | | INITIAL ENGINEERING RELEASE | 8.18.09 |
| B | C04955 | UPDATED CONNECTOR LABELS | 10.23.09 |
| C | C029865 | ADDED PIN LOCATIONS | 08.17.10 |

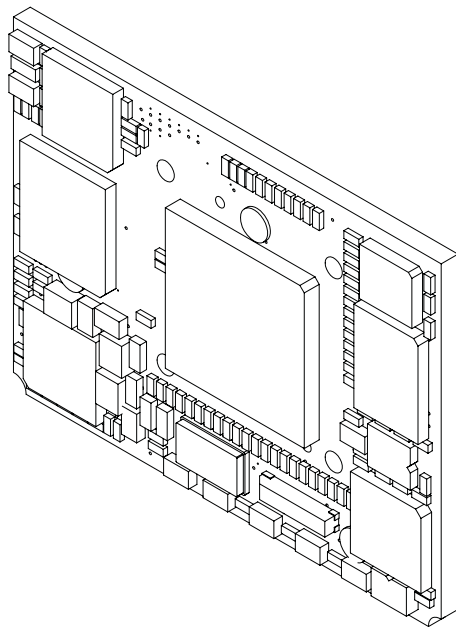


- NOTES:
1. DO NOT PLACE ANY COMPONENTS WITHIN LAYOUT AREA OF SOM
 2. BASEBOARD CONNECTOR SPECIFICATION: HIROSE DF40C-100DS-0.4V
 3. MACHINE PLACEMENT OF J1, J2, AND J3 IS HIGHLY RECOMMENDED
 4. ALL ALIGNED COMPONENTS TO BE WITHIN ± 0.075
 5. DO NOT SCALE DRAWING

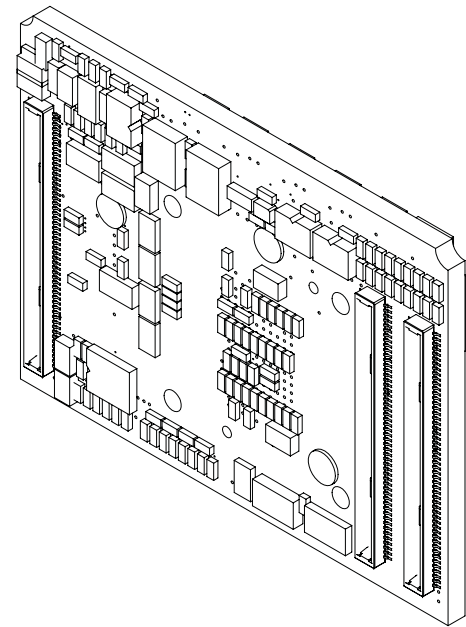


THIS DRAWING PREPARED IN ACCORDANCE WITH ASME Y14.5-2000
 ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED
 TOLERANCES UNLESS OTHERWISE SPECIFIED
 X ± 0.5
 X.X ± 0.2
 X.XX ± 0.1
 X' $\pm 1'$

| | | | | | |
|--|--|---|------------------|-----------------|-----------------|
| ENG MHC CHECK KAG MGR PMH DATE | DATE 10.23.09 DATE 10.23.09 DATE 10.23.09 DATE | <p>411 N. Washington Ave, Suite 400 Minneapolis, MN 55401 T: 612.672.9495 F: 612.672.9499 I: www.logicpd.com</p> | SIZE C | TITLE SOM-M1 | REV C |
| SCALE 4:1 | DWG NO 1013825 | | SHEET 1 OF 2 | | |

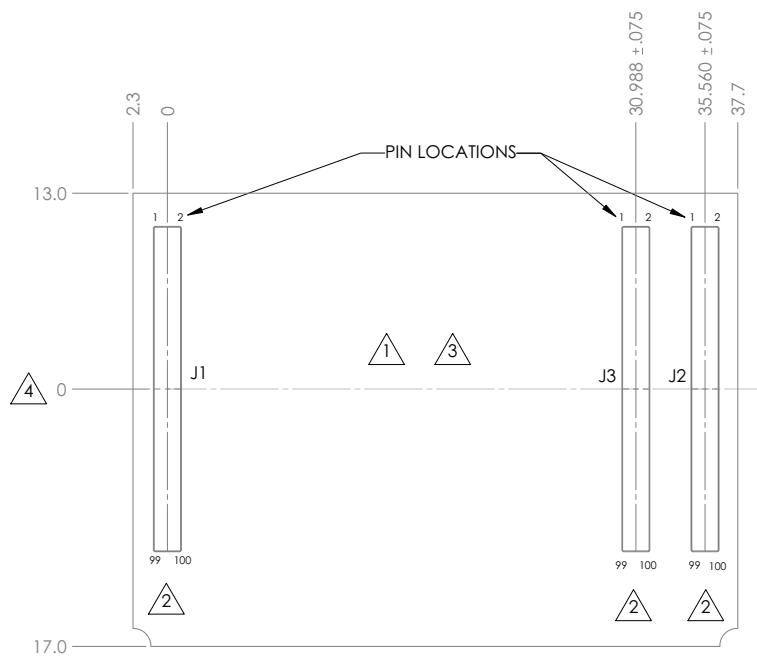


TOP



BOTTOM

ISOMETRIC VIEWS
FOR REFERENCE ONLY



RECOMMENDED BASEBOARD FOOTPRINT

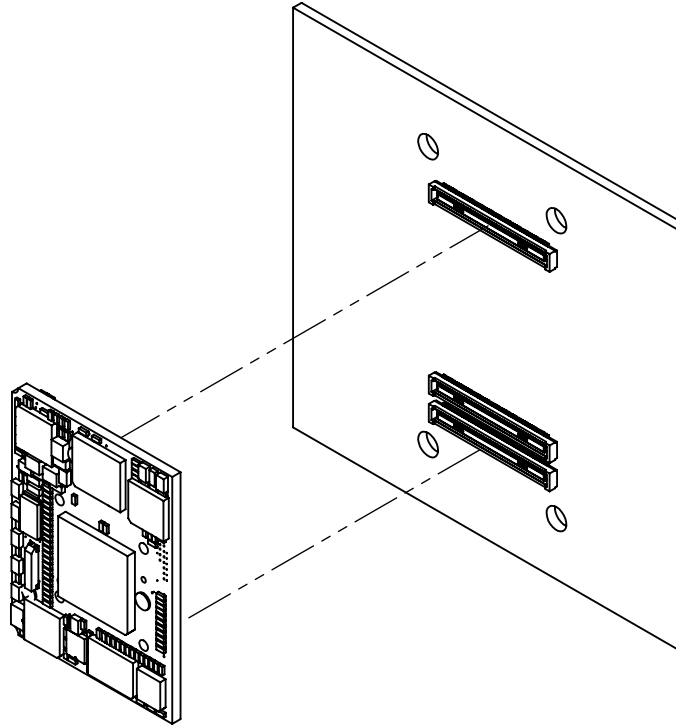
| | | |
|------------------|---------------------|-----------------|
| SIZE C | TITLE SOM-M1 | REV C |
| SCALE 4:1 | DWG. NO. 1013825 | SHEET 2 OF 2 |

Appendix B: Example Retaining Methods

| | | REVISIONS | |
|------|------------|-------------------------|----------|
| REV. | ECO NUMBER | DESCRIPTION | DATE |
| A | - | INITIAL RELEASE | 10.28.09 |
| B | C029865 | UPDATED SOM DESCRIPTION | 08.17.10 |

NOTES:

1. BASED ON TESTING A LIMITED NUMBER OF SAMPLES, THE SOM-M1 REQUIRES 10 LBS OF EXTRACTION FORCE AFTER ONE INSERTION CYCLE. AFTER 30 INSERTION AND EXTRACTION CYCLES, THIS IS REDUCED TO 7 LBS.



THIS DRAWING PREPARED IN ACCORDANCE WITH ASME Y14.5-2000


ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED

TOLERANCES UNLESS OTHERWISE SPECIFIED

X ± 0.5
 X.X ± 0.2
 X.XX ± 0.1
 X° ± 1°

THIRD ANGLE PROJECTION

| | |
|-------|----------|
| ENG | DATE |
| NWR | 10.28.09 |
| CHECK | DATE |
| KAG | 10.28.09 |
| MGR | DATE |
| PMH | 10.28.09 |
| MANF | DATE |



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| |
|--------------|
| <u>SIZE</u> |
| A |
| <u>SCALE</u> |
| 1:1 |

| |
|-------------------------------|
| <u>TITLE</u> |
| SOM-M1 Retention System- None |
| <u>DWG NO</u> |
| 1014513 |

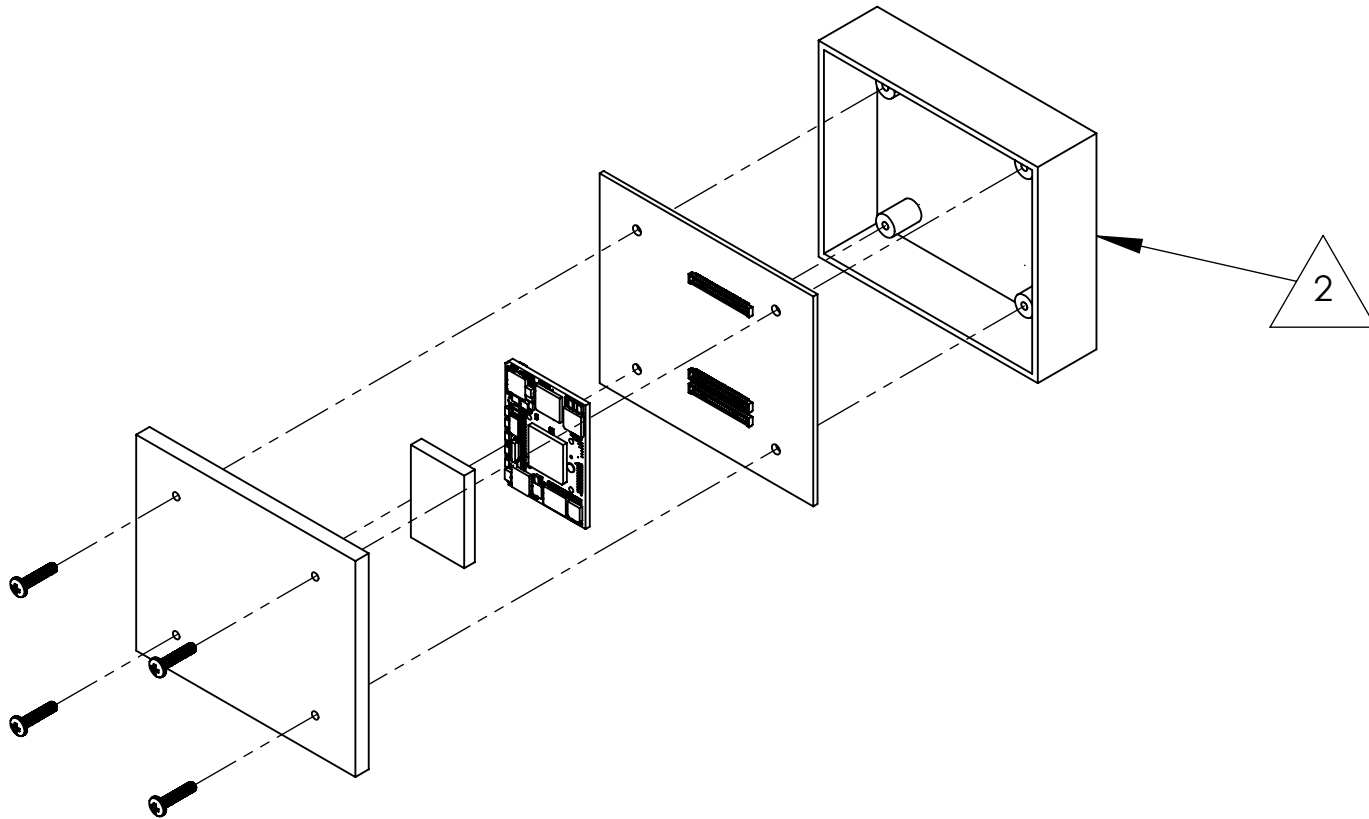
| |
|--------------|
| <u>REV</u> |
| B |
| <u>SHEET</u> |
| 1 OF 1 |

| REVISIONS | | | |
|-----------|------------|-------------------------|----------|
| REV. | ECO NUMBER | DESCRIPTION | DATE |
| A | - | INITIAL RELEASE | 10.28.09 |
| B | C029865 | UPDATED SOM DESCRIPTION | 08.17.10 |

NOTES:

1. THE SOM-M1 CAN BE RETAINED IN PLACE BY THE SURROUNDING ENCLOSURE.

2. REPRESENTATIVE ENCLOSURE



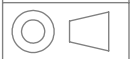
THIS DRAWING PREPARED
IN ACCORDANCE WITH
ASME Y14.5-2000

ALL DIMENSIONS
ARE IN MILLIMETERS
UNLESS OTHERWISE
SPECIFIED

TOLERANCES UNLESS
OTHERWISE SPECIFIED

| | |
|------|-------|
| X | ± 0.5 |
| X.X | ± 0.2 |
| X.XX | ± 0.1 |
| X° | ± 1° |

THIRD ANGLE PROJECTION



| | |
|-------|----------|
| ENG | DATE |
| NWR | 10.28.09 |
| CHECK | DATE |
| KAG | 10.28.09 |
| MGR | DATE |
| PMH | 10.28.09 |
| MANF | DATE |



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SIZE

A

SCALE

1:2

TITLE

SOM-M1 Retention System -
Housing

DWG NO

1014515

REV

B

SHEET

1 OF 1

| ITEM NO. | DESCRIPTION | VENDOR | PART NUMBER | Default/ QTY. |
|----------|---|---------------|-----------------------------------|------------------|
| 1 | REPRESENTATIVE PCB | N/A | N/A | 1 |
| 2 | SOM-M1 | LOGIC PD | DEPENDENT ON SOM-M1 CONFIGURATION | 1 |
| 3 | STANDOFF, M2 x 4MM | PEM | SMTSO-M2-4 | 4 |
| 4 | CLIP, RETENTION PLATE | LOGIC PD | LPD-SOM-CLIP1 | 2 |
| 5 | SCREW, PAN HEAD, M2 X 4MM | MCMaster-CARR | 92000A011 | 4 |
| 6 | THERMAL PAD, .009" THICK, ADHESIVE BACKED | LOGIC PD | LPD-SOM-CLIP1-THPAD | 2 |

| REVISIONS | | | |
|-----------|------------|-----------------|----------|
| REV. | ECO NUMBER | DESCRIPTION | DATE |
| A | C029865 | INITIAL RELEASE | 08.16.10 |

NOTES:

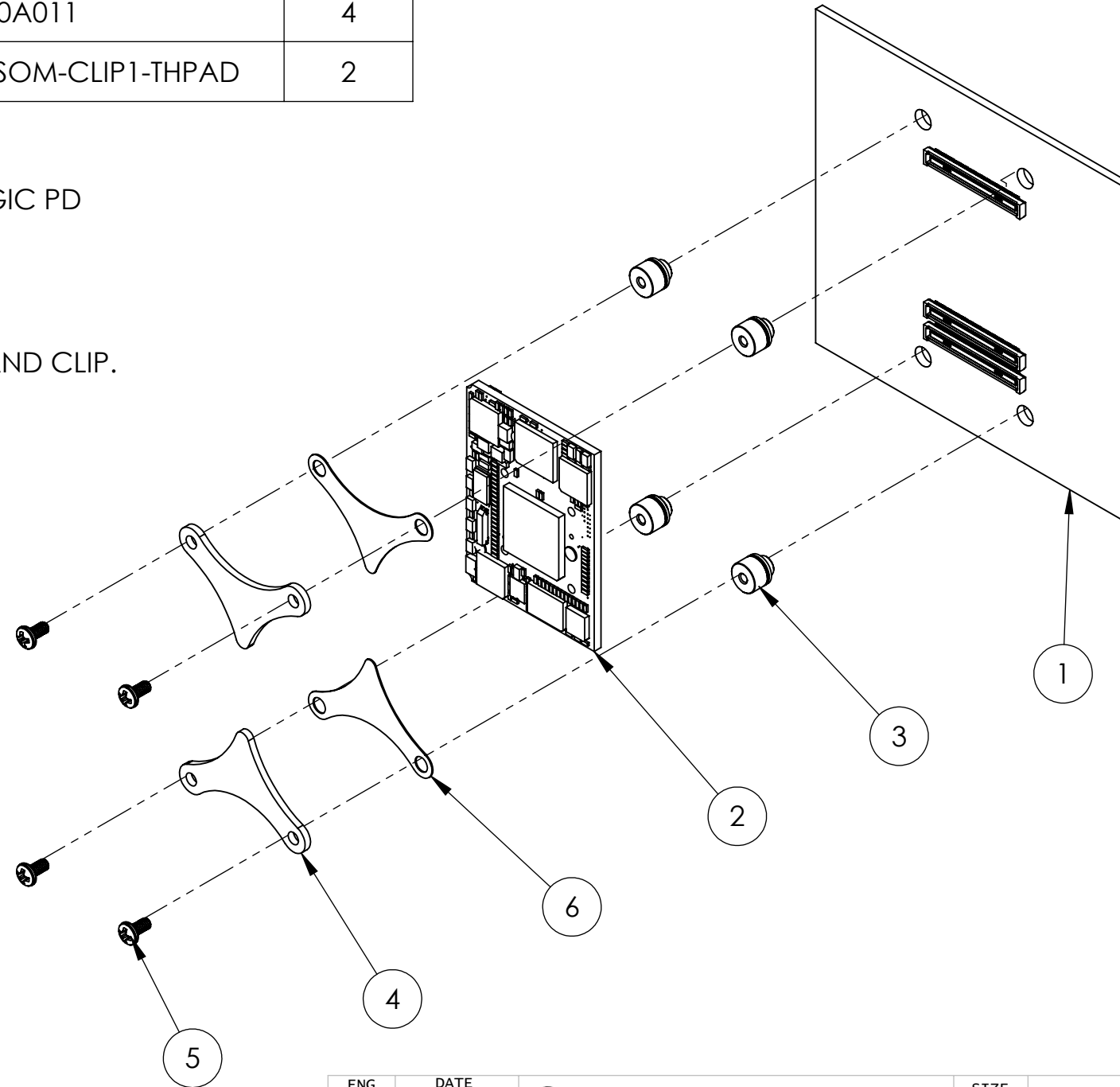
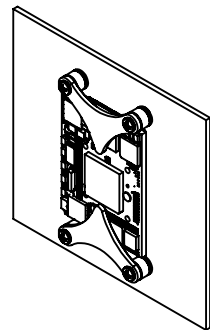
1. THIS IS THE RECOMMENDED RETENTION METHOD IF USING THE LOGIC PD RETENTION CLIP.

2. THERMAL PAD IS DIE CUT TO FIT RETENTION CLIP.

3. DO NOT PLACE COMPONENTS WITHIN LAYOUT AREA OF SOM AND CLIP.

4. BASEBOARD CONNECTOR SPECIFICATION:
HIROSE DF40C-100DS-0.4V

5. DO NOT SCALE DRAWING.



THIS DRAWING PREPARED
IN ACCORDANCE WITH
ASME Y14.5-2000

ALL DIMENSIONS
ARE IN MILLIMETERS
UNLESS OTHERWISE
SPECIFIED

TOLERANCES UNLESS
OTHERWISE SPECIFIED

X ± 0.5
X.X ± 0.2
X.XX ± 0.1
X° ± 1°

THIRD ANGLE PROJECTION

| | |
|-------|----------|
| ENG | DATE |
| NWR | 08.16.10 |
| CHECK | DATE |
| KAG | 08.16.10 |
| MGR | DATE |
| PMH | 08.16.10 |
| MANF | DATE |

LOGIC

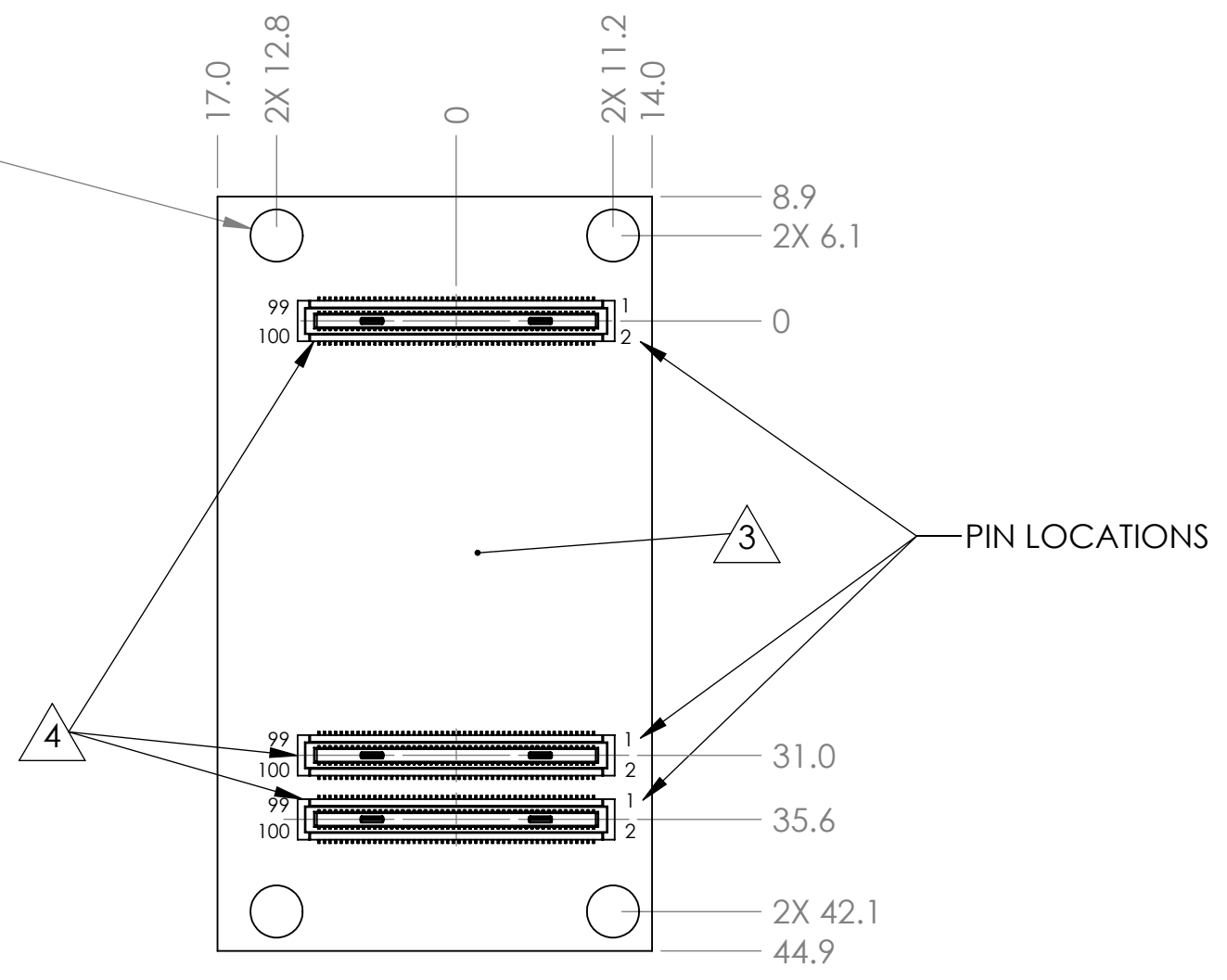
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| | | |
|----------|---------------------------------|----------|
| SIZE | TITLE | REV |
| B | SOM-M1 CLIP RETENTION SYSTEM | A |
| SCALE | DWG NO | SHEET |
| 1:1 | 1016203 | 1 OF 2 |

8 7 6 5 4 3 2 1

D
C
B
A

4X ϕ 3.7 WITH ϕ 6.2 SOLDER PAD REQUIRED.
PLATING THRU HOLE NOT REQUIRED.



RECOMMENDED BASEBOARD FOOTPRINT

| | | |
|------------------|--|-----------------|
| SIZE B | TITLE SOM-M1 CLIP RETENTION SYSTEM | REV A |
| SCALE 2:1 | DWG. NO 1016203 | SHEET 2 OF 2 |

8 7 6 5 4 3 2 1